

BOND & DETACH®



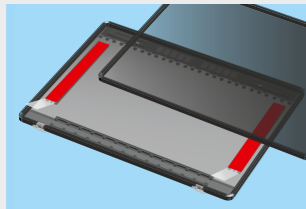
Stretch-Release Tapes for Residue-Free Removability

With our Bond & Detach® solutions the reworkability is revolutionized. This tape allows permanent mounting of components with the option to remove them without residues for repairing or recycling.

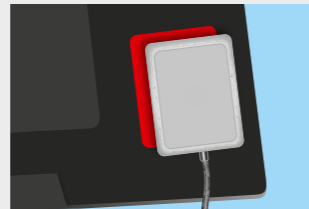
Typical applications of our Bond & Detach® assortment



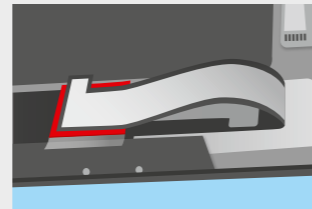
Battery mounting in mobile devices



Mounting of high value or critical components



Removable mounting of devices or accessories



Temporary fixation of components

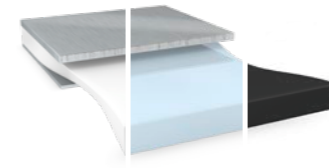
The tesa Bond & Detach® technology

Bond & Detach® is an extraordinary adhesive technology used for demanding bonding applications that provides the **option to be removed residue-free by stretching**. The unique and patented technology was developed by tesa and offers the possibility of **simple and secure reworkability**

during the entire product life cycle of an electronic device – from production to end of life. Besides that the whole Bond & Detach® assortment provides **very good impact resistance and bonding strength, even on LSE substrates**.

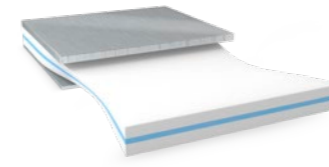
tesa Bond & Detach® 704xx/703xx/706xx

These series are designed for applications demanding high bonding strength and reworkability. They have the best bonding performance within the Bond & Detach® assortment. The black series 706xx offers good light-blocking properties.



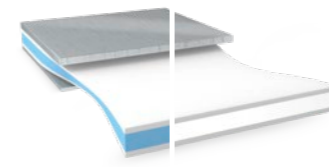
tesa Bond & Detach® 672xx

The special cushioning adhesive used for the 672xx series provides improved impact resistance. The removability of these products is also improved by the stretchable PU backing used.



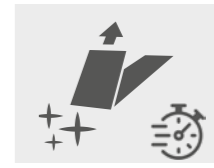
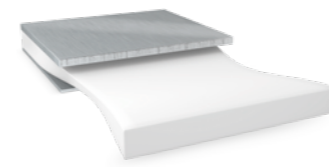
tesa Bond & Detach® 770xx/648xx

The performance of these highly impact-resistant and very tacky series is based on the innovative tesa foaming technology. The new developed backing further improves the removability of these products by enhancing the tear resistance and reducing the force required to remove the tape.

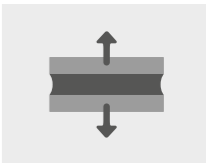


tesa Bond & Detach® 705xx NEW

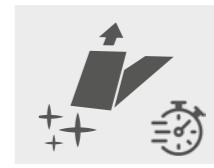
The latest tesa Bond & Detach® 705xx series is a further development of the very successful 704xx series. The adhesive has been modified to provide excellent adhesion and resistance to shear and repulsive forces even at elevated temperatures.



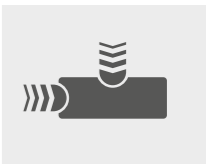
Fast & residue-free removal



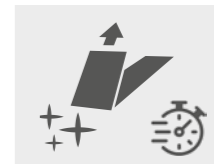
Best bonding



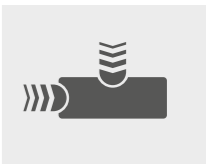
Fast & residue-free removal



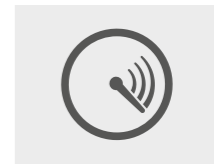
Impact resistance



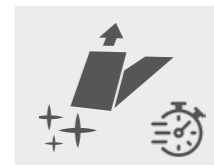
Fast & residue-free removal



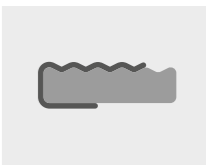
Impact resistance



Quick bonding



Fast & residue-free removal



Anti-repulsion



Shear resistance